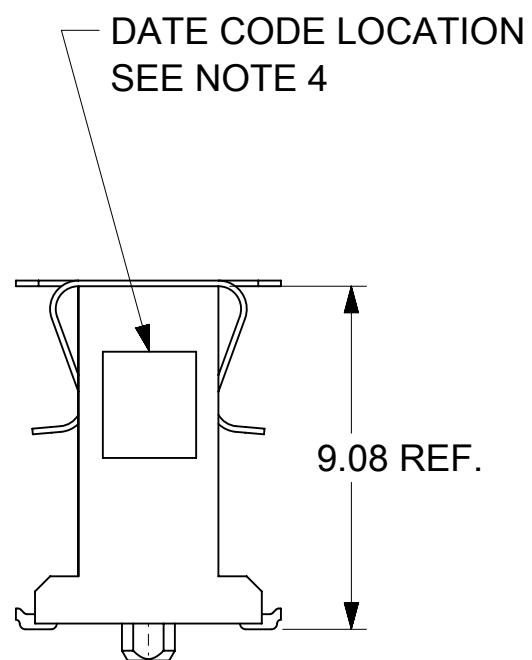
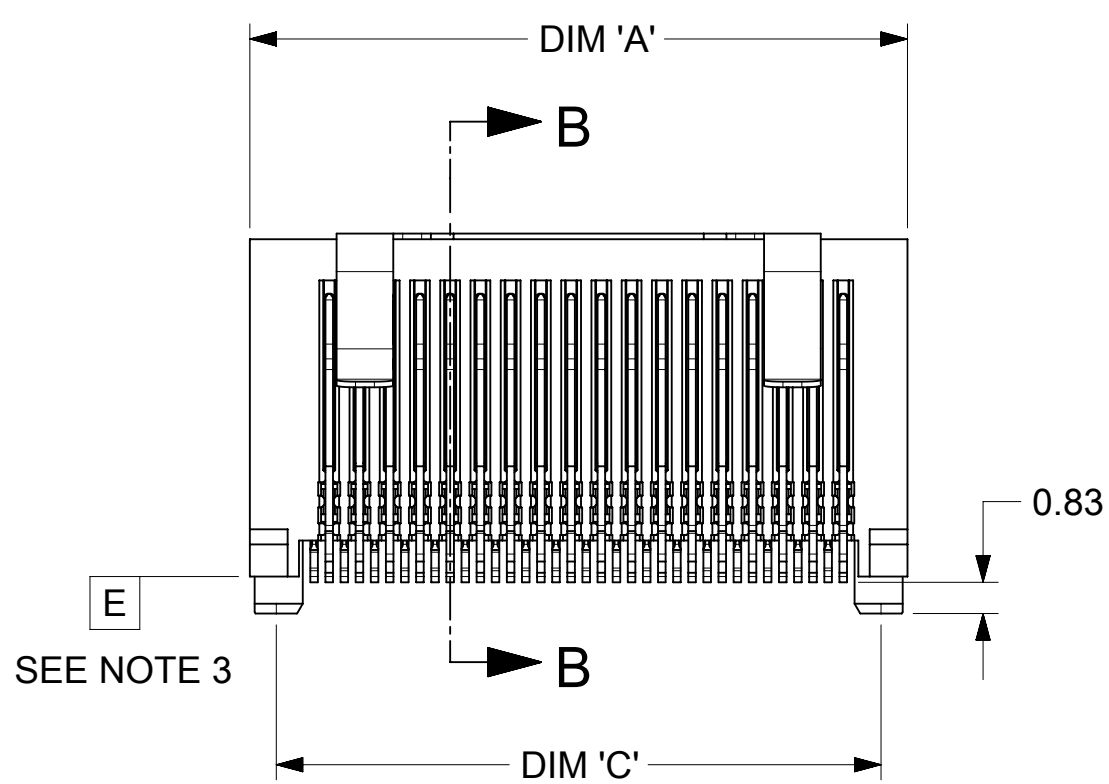
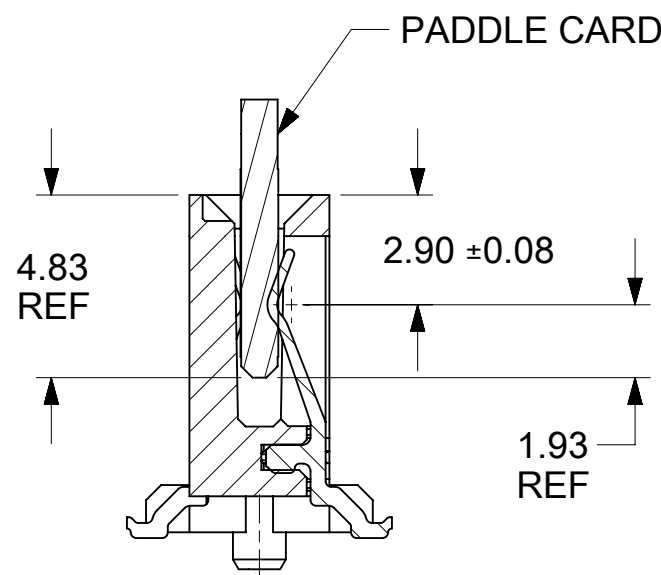
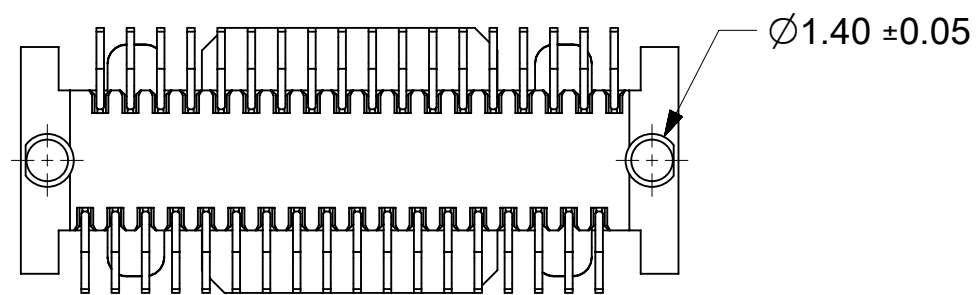


36 CIRCUIT ASSEMBLY SHOWN

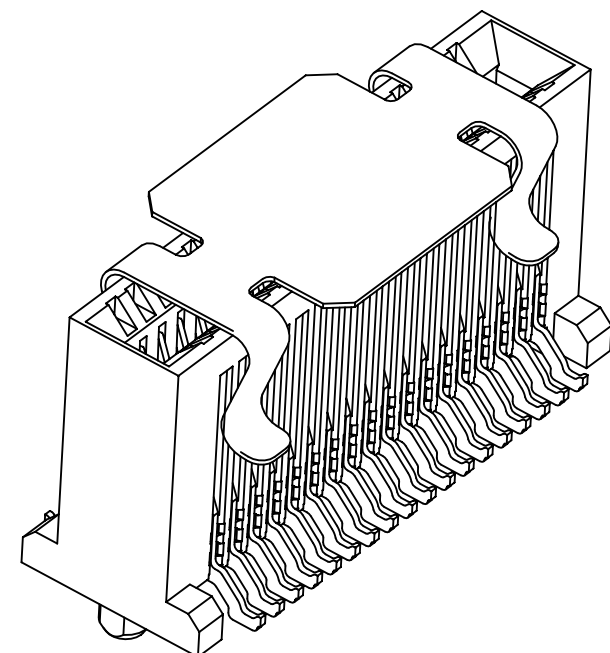


NOTES:

1. MATERIAL:
HOUSING - HIGH TEMPERATURE THERMOPLASTIC GLASS FILLED, UL 94V-0, BLACK
TERMINALS - COPPER ALLOY
2. TERMINAL PLATING:
OPTION 1
CONTACT AREA: 0.38μm HARD GOLD OVER 2.54μm NICKEL
SOLDER AREA: 2.54-5.09μm TIN OVER 1.27μm NICKEL
OPTION 2
CONTACT AREA: 0.76μm HARD GOLD OVER 2.54μm NICKEL
SOLDER AREA: 2.54-5.09μm TIN OVER 1.27μm NICKEL
3. TERMINAL SOLDER FEET TO BE COPLANAR WITHIN 0.10/.004 MEASURED FROM FRONT HOUSING STANDOFF (DATUM E)
4. DATE CODE: 4 DIGIT (3 DIGIT DAY, 1 DIGIT YEAR)
5. CIRCUIT IDENTIFIER: SEE APPROPRIATE INDUSTRY SPECIFICATION FOR LOCATION OF PIN 1
6. MATES WITH:
A. INTERNAL CABLE SERIES:
79575/74563/79576/74573/79536/74562/74569/74586
B. PADDLE CARD PCB: DO NOT BOTTOM OUT PCB IN THE CONNECTOR. SEE SECTION Z-Z.
- USE WITH APPROPRIATE INTERNAL SHELL FROM SD-76010-002
7. LITTLE ROCK PACKAGING PER PK-75577-001
CHENGDU PACKAGING PER PK-75577-002
8. CONFORMS TO PRODUCT SPECIFICATION PS-75783-001
9. CONFORMS TO APPLICATION SPECIFICATION AS-75783-001



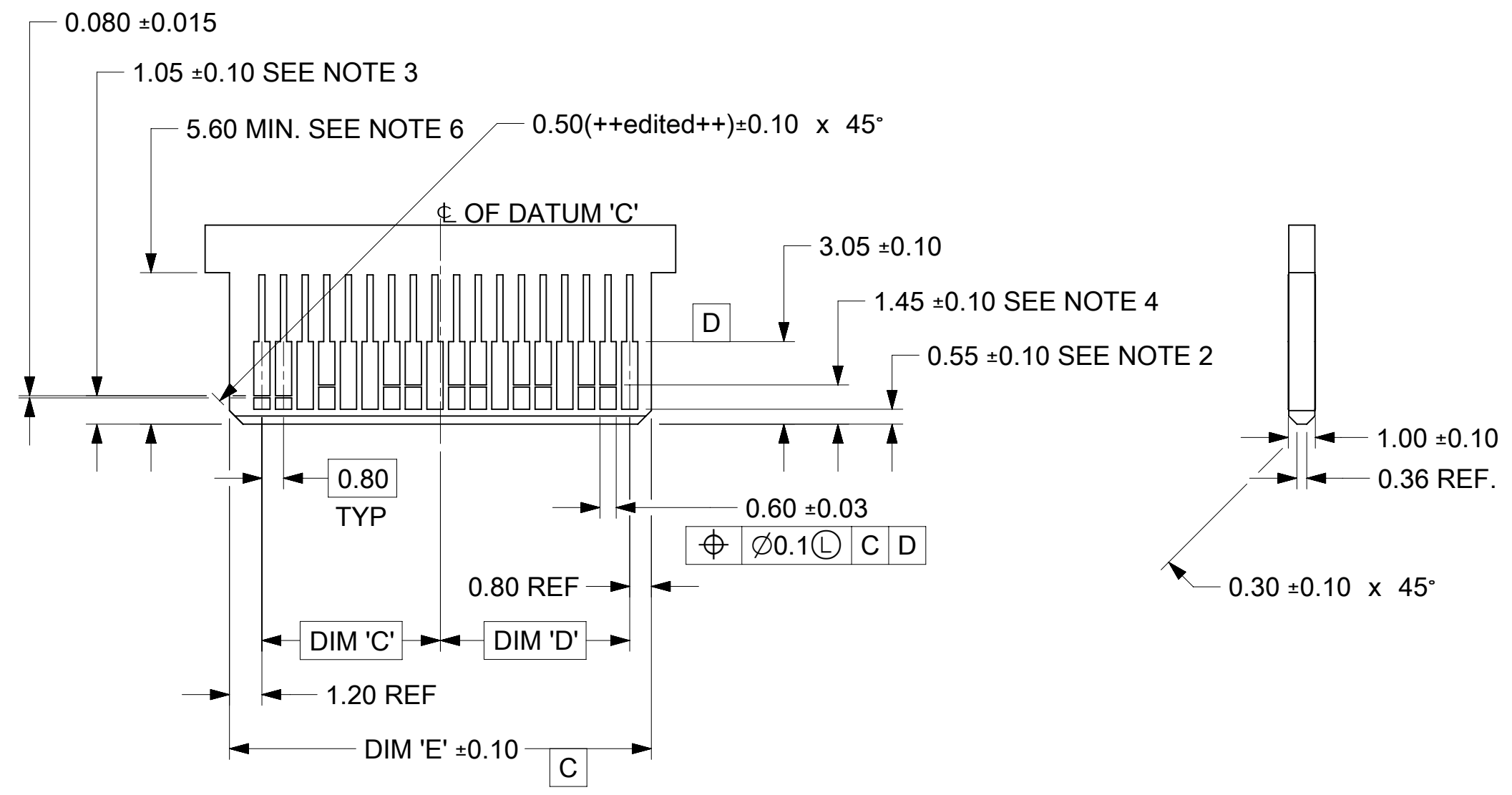
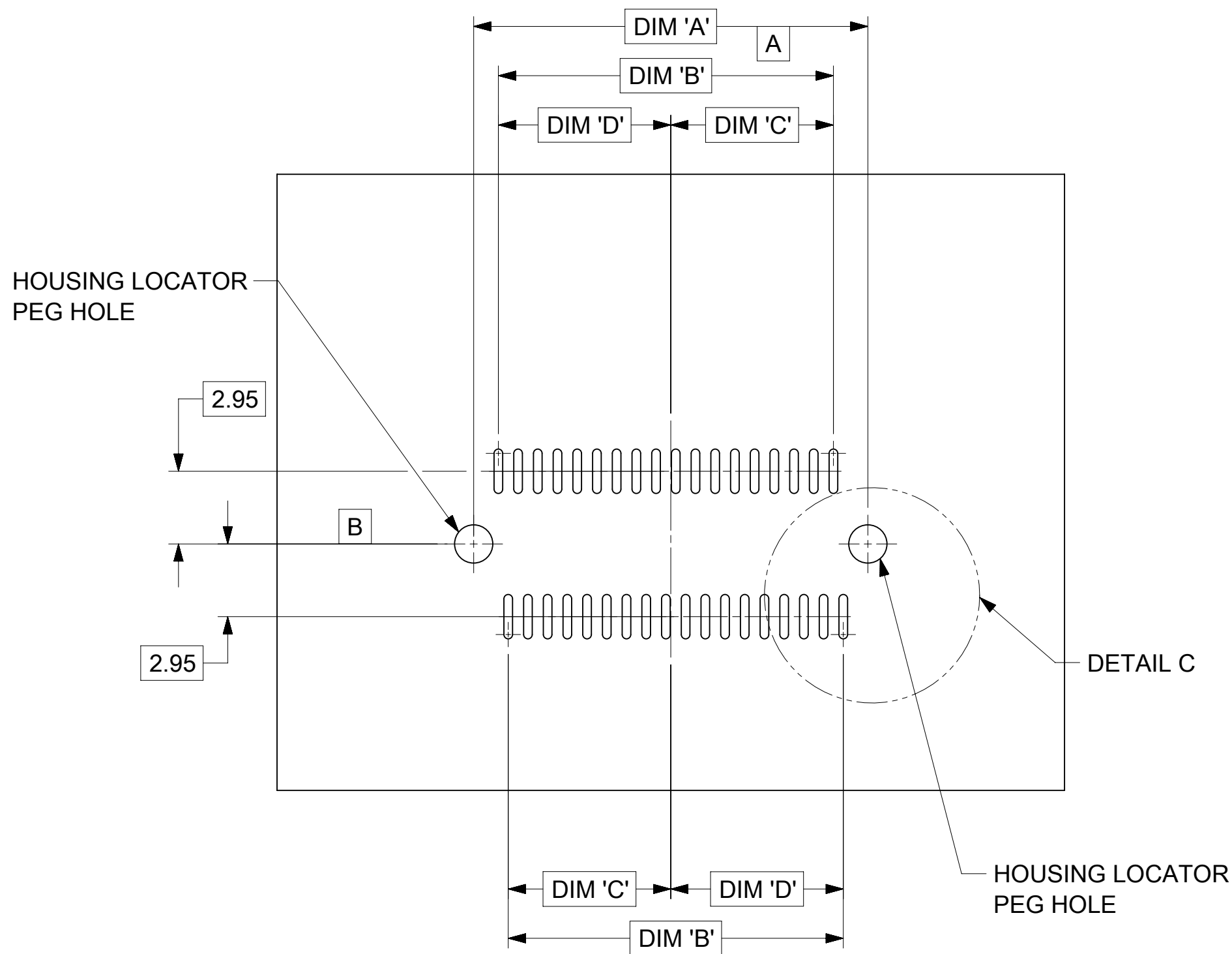
SECTION B-B



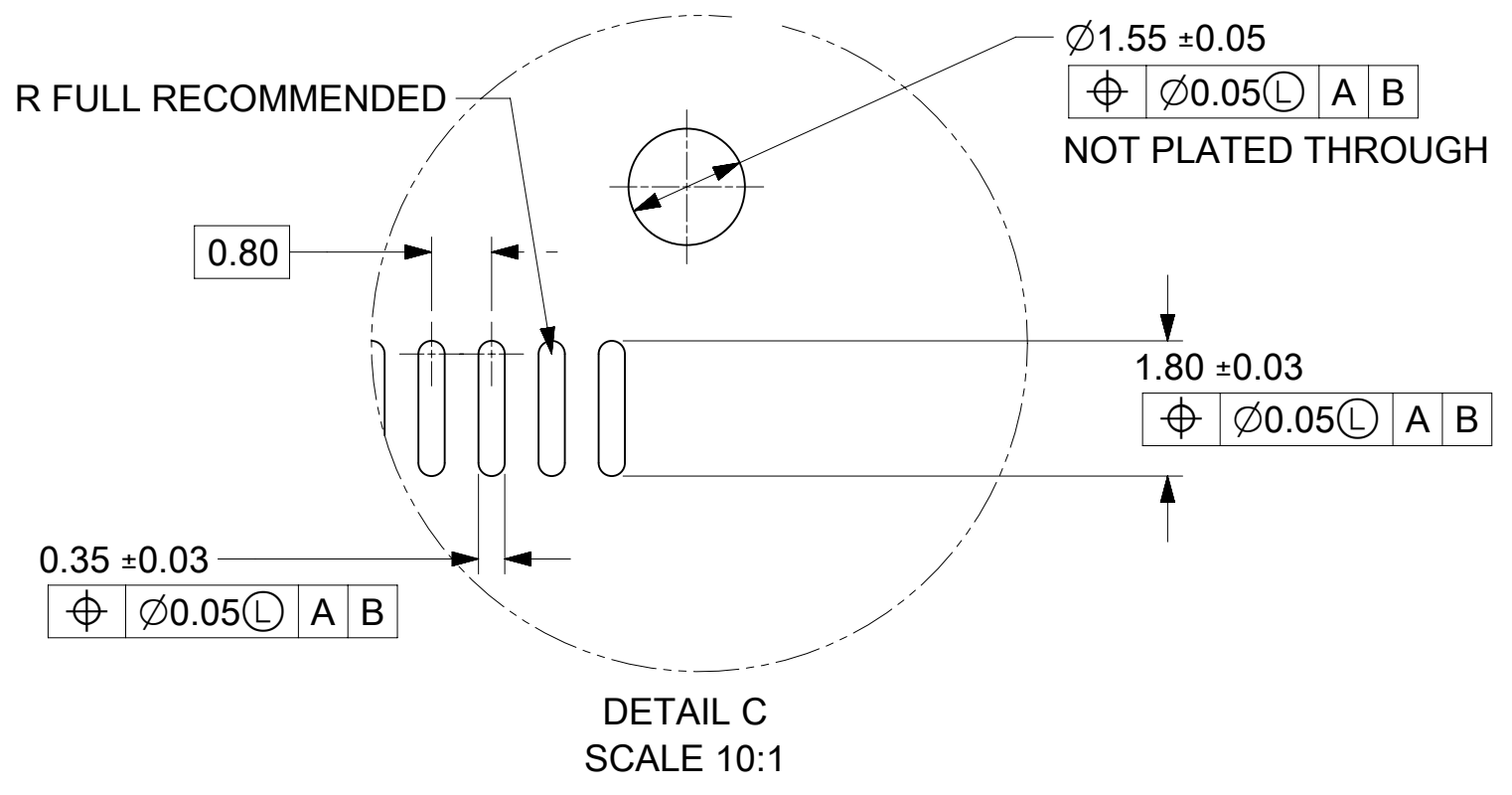
CIRCUIT SIZE	MAT'L NUMBER	PLATING OPTION	DIM 'A'	DIM 'B'	DIM 'C'
26	75577-1001	OPTION 1	13.40	11.80	12.00
26	75577-1005	OPTION 2	13.40	11.80	12.00
36	75577-1002	OPTION 1	17.40	15.80	16.00
36	75577-1006	OPTION 2	17.40	15.80	16.00
50	75577-1003	OPTION 1	23.00	21.40	21.60
50	75577-1007	OPTION 2	23.00	21.40	21.60
68	75577-1004	OPTION 1	30.20	28.60	28.80

THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION

DIMENSION UNITS mm	SCALE 5:1	CURRENT REV DESC: OBSOLETE PART NUMBER AS PER PCN#510579	molex		
GENERAL TOLERANCES (UNLESS SPECIFIED)		EC NO: 675088			
4 PLACES ±	MM INCH	DRWN: SUGEEB 2021/08/02	PRODUCT CUSTOMER DRAWING		
3 PLACES ±		CHK'D: GGA 2021/09/08	DOCUMENT NUMBER		
2 PLACES ± 0.13		APPR: GGA 2021/09/08	SD-75577-002		
1 PLACE ± 0.25		INITIAL REVISION:	DOC TYPE	DOC PART	REVISION
0 PLACES ±		DRWN: JLSWENSON 06/07/07	PSD	001	E
ANGULAR TOL ± 0.5 °		APPR: MBANAKIS 06/07/07	MATERIAL NUMBER	CUSTOMER	SHEET NUMBER
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	THIRD ANGLE PROJECTION	DRAWING C-SIZE	75577	GENERAL MARKET	1 OF 2



36 CIRCUIT SHOWN
PATTERN FOR REPRESENTATION ONLY



- NOTES:
- FOR APPROPRIATE SHELL FOOT PRINT AND KEEP OUT AREAS, SEE SD-76010-002
 - PAD CONFIGURATION FOR FIRST MATE
 - PAD CONFIGURATION FOR SECOND MATE
 - PAD CONFIGURATION FOR THIRD MATE (HIGH SPEED SIGNALS)
 - FOR PIN ASSIGNMENTS AND MATING SEQUENCE (1ST, 2ND, 3RD), SEE APPLICABLE SPECIFICATION
 - MINIMUM STEP REQUIRED IF PCB MADE WIDER THAN CARD TONGUE
 - THESE ARE GENERIC DETAILS THAT DESCRIBES THE CONFIGURATION OF VARIOUS PCB DESIGN ELEMENTS. THE CUSTOMER MUST DETERMINE WHERE AND WHEN TO USE EACH ELEMENT TO ACCOMODATE THEIR SPECIFIC APPLICATION.
 - CHAMFER ROUGHNESS NOT TO EXCEED 3.17µM.
 - EDGECARD CHAMFER NOT TO GO THROUGH GOLD PAD.

CIRCUIT SIZE	DIMENSIONS				
	DIM 'A'	DIM 'B'	DIM 'C'	DIM 'D'	DIM 'E'
26	12.00	9.60	4.60	5.00	11.60
36	16.00	13.60	6.60	7.00	15.60
50	21.60	19.20	9.40	9.80	21.20
68	28.80	26.40	13.00	13.40	28.40

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DIMENSION UNITS	SCALE	CURRENT REV DESC: OBSOLETE PART NUMBER AS PER PCN#510579	molex		
mm	5:1				
GENERAL TOLERANCES (UNLESS SPECIFIED)			SALES DRAWING IPASS VERTICAL CONNECTOR .8 MM PITCH I/O		
4 PLACES	±	±	PRODUCT CUSTOMER DRAWING		
3 PLACES	±	±	DOCUMENT NUMBER		
2 PLACES	± 0.13	±	SD-75577-002		
1 PLACE	± 0.25	±	DOC TYPE		
0 PLACES	±	±	PSD		
ANGULAR TOL	± 0.5°		DOC PART		
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	THIRD ANGLE PROJECTION	DRAWING	001		
		SERIES	E		
		C-SIZE	SHEET NUMBER		
		75577	2 OF 2		